

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A module component comprising:
 - a substrate
 - a partition formed on the substrate, the partition having a predetermined height to divide the substrate into a plurality of circuit blocks;
 - a first sealing member covering a first circuit block of the plurality of circuit blocks;
 - a second sealing member covering a second circuit block of the plurality of circuit blocks;
 - a first conductive film covering at least a surface of the first sealing member; and
 - a second conductive film covering at least a surface of the second sealing member;
 - wherein the plurality of circuit blocks are electrically shielded individually; and the partition is made of a composition of a resin and a conductive material.
2. (Currently Amended) The module component according to claim 1, wherein the substrate is made of resin;
 - ~~the partition is made of resin and conductive material; and~~
 - the first sealing member, the second sealing member and the partition contain a same resin.
3. (Currently Amended) The module component according to claim 1, wherein the substrate is ceramic;

the ~~partition-composition~~ is made of ceramic powder-containing resin and conductive material; and

the first sealing member, the second sealing member and the partition contain a same resin.

4. (Cancelled)

5. (Original) The module component according to claim 2, wherein

the conductive material of the partition is a conductive resin.

6. (Original) The module component according to claim 1, wherein

the partition is resin having a metal film formed on an outer surface thereof, and has a square cross section in a longitudinal direction.

7. (Cancelled)

8. (Original) The module component according to claim 1, wherein

the partition has a conductive wall in a direction vertical to the substrate.

9. (Cancelled)

10. (Original) The module component according to claim 1, wherein

the partition has resin at least one side surface thereof.

11. (Original) The module component according to claim 1, wherein

the partition is positioned inside the substrate, and has a planar shape of one of a circle and a polygon.

12. (Original) The module component according to claim 11, wherein

the partition is positioned out of contact with an outer edge of the substrate.

13. (Original) The module component according to claim 1, wherein

the partition has a planar shape of a letter T.

14. (Currently Amended) The module component according to claim 1, wherein

either a) the first conductive film and the second conductive film include metal or b) the first conductive film and the second conductive film include and-conductive resin.

15. (Original) The module component according to claim 1, wherein

the partition is higher than an electric component mounted on the substrate.

16. (Previously Presented) The module component according to claim 1, wherein

the substrate has a ground pattern on a surface thereof, and the ground pattern is connected with the first conductive film and the second conductive film.

17. (Currently Amended) A method for manufacturing a module component having a plurality of circuit blocks shielded individually, the method comprising:

a step of mounting a partition made of resin and conductive material higher than mounting components, the partition dividing the mounting components and a substrate into a plurality of circuit blocks on the substrate;

a step of forming a first sealing member covering a first circuit block of the plurality of circuit blocks individually in such a manner as to be higher than the mounting components;

a step of forming a second sealing member covering a second circuit block of the plurality of circuit blocks individually in such a manner as to be higher than the mounting components;

a step of forming a first conductive film on a surface of the first sealing member; and

a step of forming a second conductive film on a surface of the second sealing member.

18. (Previously Presented) The method for manufacturing the module component according to claim 17,

wherein

the partition contains a conductive material formed in a direction vertical to the substrate; and

the step of forming a first sealing member or the step of forming a first sealing member includes a step of polishing the respective sealing member so as to expose the conductive material on a surface.

19. (Original) The method for manufacturing the module component according to claim 17 further comprising:

a step of removing the conductive material formed in a top of the partition by one of dicing and laser.

20. (Previously Presented) The method for manufacturing the module component according to claim 17, wherein

the step of forming a first conductive film or the step of forming a second conductive film includes a step of connecting the respective conductive film with a ground pattern.

21. (Previously Presented) The module component according to claim 1, wherein the first and second conductive films are separated by the partition.

22. (Previously Presented) The module component according to claim 1, wherein the partition electrically connects the first conductive film with the second conductive film.